

IGBT – Power, Co-PAK N-Channel, Field Stop VII (FS7), TO247-4L 1200 V, 1.7 V, 140 A FGY4L140T120SWD

Description

Using the novel field stop 7th generation IGBT technology and the Gen7 Diode in TO247 4-lead package, FGY4L140T120SWD offers the optimum performance with low switching and conduction losses for high-efficiency operations in various applications like Solar Inverter, UPS and ESS.

Features

- Maximum Junction Temperature $T_J = 175^{\circ}\text{C}$
- Positive Temperature Coefficient for Easy Parallel Operation
- High Current Capability
- Smooth and Optimized Switching
- Low Switching Loss
- RoHS Compliant

Applications

- Solar Inverter
- UPS
- Energy Storage System

MAXIMUM RATINGS ($T_J = 25^{\circ}\text{C}$ unless otherwise noted)

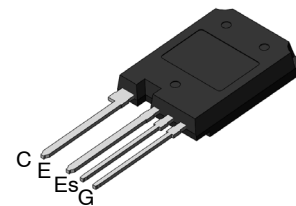
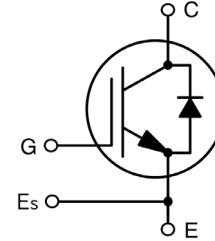
Parameter	Symbol	Value	Unit
Collector-to-Emitter Voltage	V_{CE}	1200	V
Gate-to-Emitter Voltage	V_{GE}	± 20	
Transient Gate-to-Emitter Voltage		± 30	
Collector Current	I_C	$T_C = 25^{\circ}\text{C}$ (Note 1)	A
		$T_C = 100^{\circ}\text{C}$	
Power Dissipation	P_D	$T_C = 25^{\circ}\text{C}$	W
		$T_C = 100^{\circ}\text{C}$	
Pulsed Collector Current	I_{CM}	$T_C = 25^{\circ}\text{C}$, $t_p = 10 \mu\text{s}$ (Note 2)	A
Diode Forward Current	I_F	$T_C = 25^{\circ}\text{C}$ (Note 1)	A
		$T_C = 100^{\circ}\text{C}$	
Pulsed Diode Forward Current	I_{FM}	$T_C = 25^{\circ}\text{C}$, $t_p = 10 \mu\text{s}$ (Note 2)	A
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to $+175$	$^{\circ}\text{C}$
Lead Temperature for Soldering Purposes	T_L	265	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Value limited by bond wire
2. Repetitive rating: Pulse width limited by max. junction temperature.

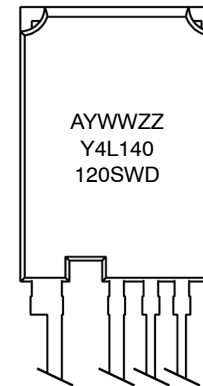
BV_{CES}	$V_{CE(SAT_TYP)}$	I_C
1200 V	1.7 V	140 A

PIN CONNECTIONS



TO-247-4LD
CASE 340BW

MARKING DIAGRAM



A = Assembly Location
YWW = Date code (Year & week)
ZZ = Assembly Lot
Y4L140120SWD = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
FGY4L140T120SWD	TO-247-4LD (Pb-Free)	30 Units / Tube

FGY4L140T120SWD

THERMAL CHARACTERISTICS

Parameter	Symbol	Value			Unit
		Min	Typ	Max	
Thermal Resistance, Junction-to-Case for IGBT	$R_{\theta JC}$	–	0.09	0.12	°C/W
Thermal Resistance, Junction-to-Case for Diode	$R_{\theta JCD}$	–	0.15	0.2	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	–	–	40	

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector-to-Emitter Breakdown Voltage	BV_{CES}	$V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$	1200	–	–	V
Breakdown Voltage Temperature Coefficient	$\frac{\Delta BV_{CES}}{\Delta T_J}$	$V_{GE} = 0\text{ V}, I_C = 9.99\text{ mA}$	–	1256	–	mV/°C
Collector-to-Emitter Cut-Off Current	I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$	–	–	40	μA
Gate-to-Emitter Leakage Current	I_{GES}	$V_{GE} = \pm 20\text{ V}, V_{CE} = 0\text{ V}$	–	–	±400	nA

ON CHARACTERISTICS

Gate-to-Emitter Threshold Voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 140\text{ mA}$	5.6	6.5	7.4	V
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE} = 15\text{ V}, I_C = 140\text{ A}, T_J = 25^\circ\text{C}$	–	1.7	2.0	
		$V_{GE} = 15\text{ V}, I_C = 140\text{ A}, T_J = 175^\circ\text{C}$	–	2.4	–	

DYNAMIC CHARACTERISTICS

Input Capacitance	C_{ies}	$V_{CE} = 30\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	–	13600	–	pF
Output Capacitance	C_{oes}		–	389	–	
Reverse Transfer Capacitance	C_{res}		–	53.2	–	
Total Gate Charge	Q_g	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}, I_C = 140\text{ A}$	–	426	–	nC
Gate-to-Emitter Charge	Q_{ge}		–	114	–	
Gate-to-Collector Charge	Q_{gc}		–	148	–	

SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Turn-on Delay Time	$t_{d(on)}$	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}, I_C = 70\text{ A}, R_G = 4.7\ \Omega, T_J = 25^\circ\text{C}$	–	56	–	ns
Rise Time	t_r		–	16	–	
Turn-off Delay Time	$t_{d(off)}$		–	254.4	–	
Fall Time	t_f		–	65.6	–	
Turn-on Switching Loss	E_{on}	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}, I_C = 140\text{ A}, R_G = 4.7\ \Omega, T_J = 25^\circ\text{C}$	–	2.2	–	mJ
Turn-off Switching Loss	E_{off}		–	2.1	–	
Total Switching Loss	E_{ts}		–	4.2	–	
Turn-on Delay Time	$t_{d(on)}$		–	60.8	–	ns
Rise Time	t_r		–	27.2	–	
Turn-off Delay Time	$t_{d(off)}$		–	232	–	
Fall Time	t_f		–	57.6	–	
Turn-on Switching Loss	E_{on}	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}, I_C = 140\text{ A}, R_G = 4.7\ \Omega, T_J = 25^\circ\text{C}$	–	3.9	–	mJ
Turn-off Switching Loss	E_{off}		–	4.6	–	
Total Switching Loss	E_{ts}		–	8.5	–	

FGY4L140T120SWD

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Turn-on Delay Time	$t_{d(on)}$	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}$ $I_C = 70\text{ A } R_G = 4.7\ \Omega, T_J = 175^\circ\text{C}$	–	49.6	–	ns
Rise Time	t_r		–	22.4	–	
Turn-off Delay Time	$t_{d(off)}$		–	305.6	–	
Fall Time	t_f		–	107.2	–	
Turn-on Switching Loss	E_{on}		–	4.8	–	mJ
Turn-off Switching Loss	E_{off}		–	3.0	–	
Total Switching Loss	E_{ts}		–	7.9	–	
Turn-on Delay Time	$t_{d(on)}$	$V_{CE} = 600\text{ V}, V_{GE} = 15\text{ V}$ $I_C = 140\text{ A } R_G = 4.7\ \Omega, T_J = 175^\circ\text{C}$	–	52.8	–	ns
Rise Time	t_r		–	35.2	–	
Turn-off Delay Time	$t_{d(off)}$		–	280	–	
Fall Time	t_f		–	99.6	–	
Turn-on Switching Loss	E_{on}		–	8.6	–	mJ
Turn-off Switching Loss	E_{off}		–	7.0	–	
Total Switching Loss	E_{ts}		–	15.5	–	

DIODE CHARACTERISTICS

Forward Voltage	V_F	$I_F = 140\text{ A}, T_J = 25^\circ\text{C}$	1.74	2.04	2.34	V
		$I_F = 140\text{ A}, T_J = 175^\circ\text{C}$	–	2.2	–	

DIODE SWITCHING CHARACTERISTICS, INDUCTIVE LOAD

Reverse Recovery Time	t_{rr}	$V_R = 600\text{ V}, I_F = 70\text{ A},$ $di_F/dt = 1000\text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	–	192.4	–	ns
Reverse Recovery Charge	Q_{rr}		–	4.4	–	μC
Reverse Recovery Energy	E_{REC}		–	1.5	–	mJ
Peak Reverse Recovery Current	I_{RRM}		–	45.9	–	A
Reverse Recovery Time	t_{rr}	$V_R = 600\text{ V}, I_F = 140\text{ A},$ $di_F/dt = 1000\text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	–	266.9	–	ns
Reverse Recovery Charge	Q_{rr}		–	6.95	–	μC
Reverse Recovery Energy	E_{REC}		–	2.4	–	mJ
Peak Reverse Recovery Current	I_{RRM}		–	52.4	–	A
Reverse Recovery Time	t_{rr}	$V_R = 600\text{ V}, I_F = 70\text{ A},$ $di_F/dt = 1000\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	–	304.6	–	ns
Reverse Recovery Charge	Q_{rr}		–	10.6	–	μC
Reverse Recovery Energy	E_{REC}		–	3.9	–	mJ
Peak Reverse Recovery Current	I_{RRM}		–	68.7	–	A
Reverse Recovery Time	t_{rr}	$V_R = 600\text{ V}, I_F = 140\text{ A},$ $di_F/dt = 1000\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	–	431.9	–	ns
Reverse Recovery Charge	Q_{rr}		–	16.3	–	μC
Reverse Recovery Energy	E_{REC}		–	6.1	–	mJ
Peak Reverse Recovery Current	I_{RRM}		–	76.6	–	A

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

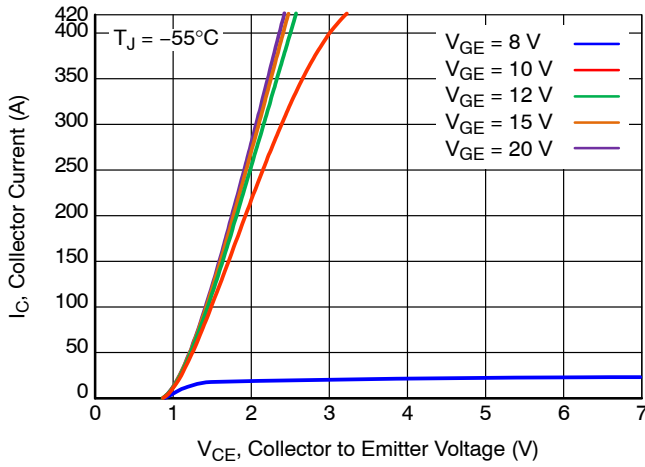


Figure 1. Output Characteristics

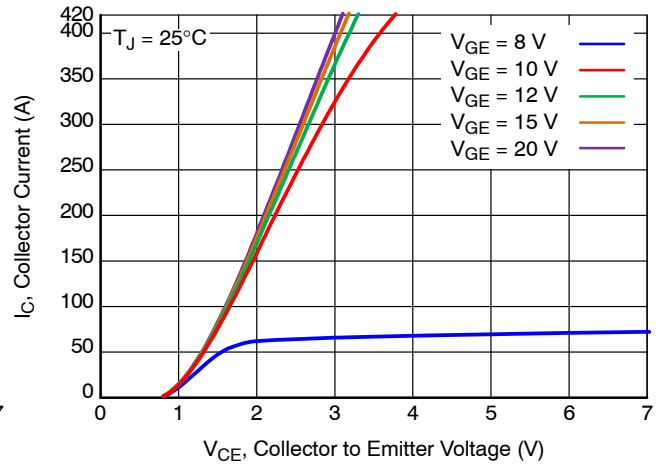


Figure 2. Output Characteristics

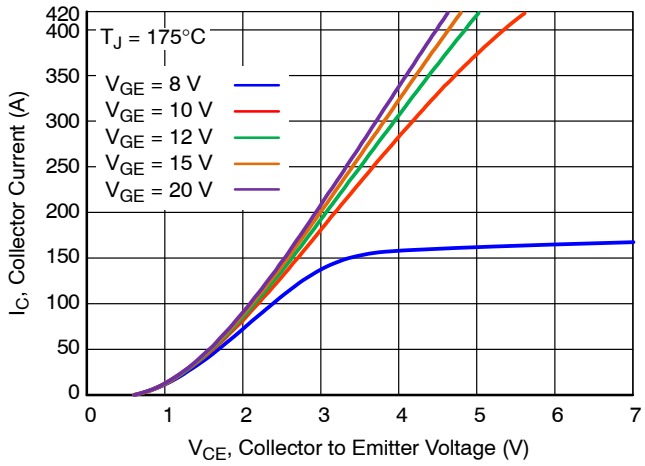


Figure 3. Output Characteristics

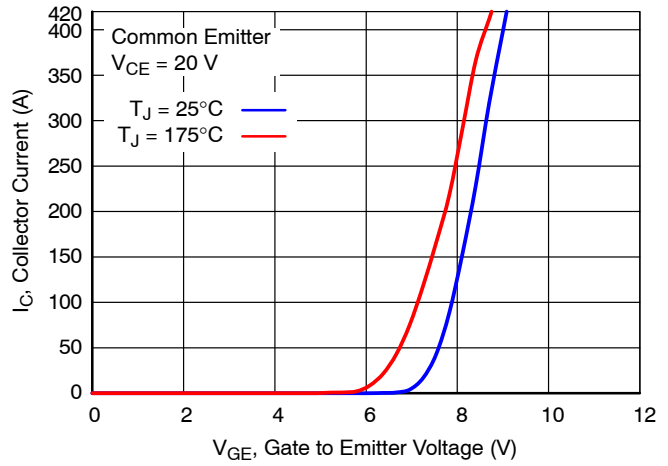


Figure 4. Transfer Characteristics

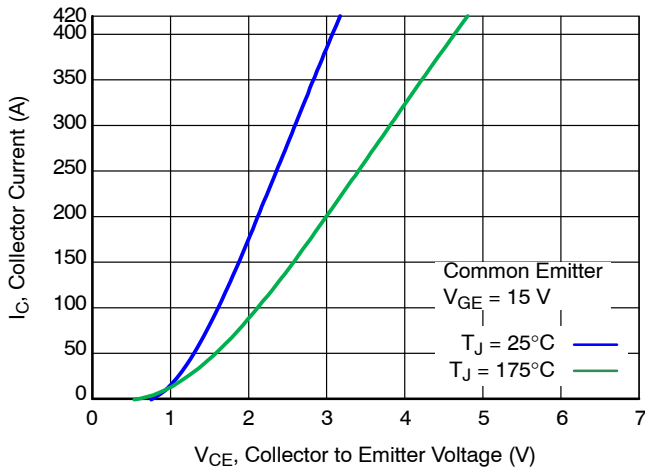


Figure 5. Saturation Characteristics

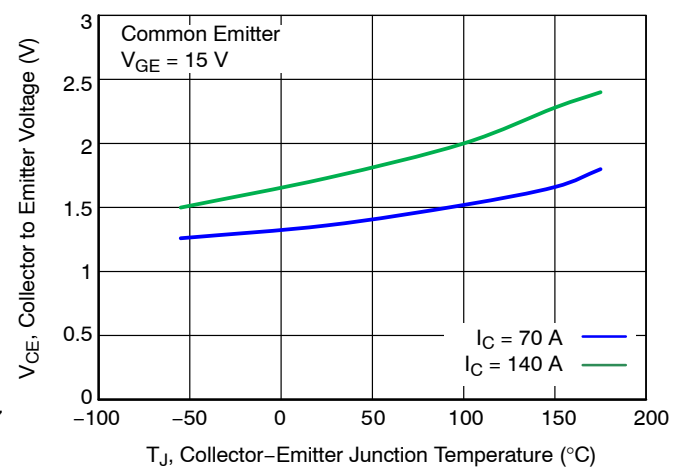


Figure 6. Saturation Voltage vs. Junction Temperature

TYPICAL CHARACTERISTICS

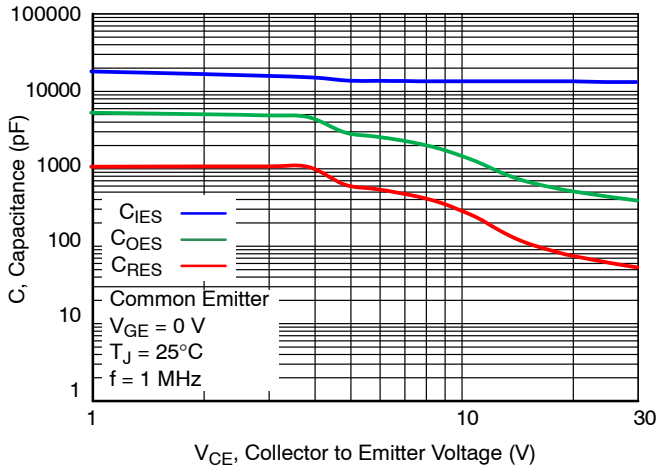


Figure 7. Capacitance Characteristics

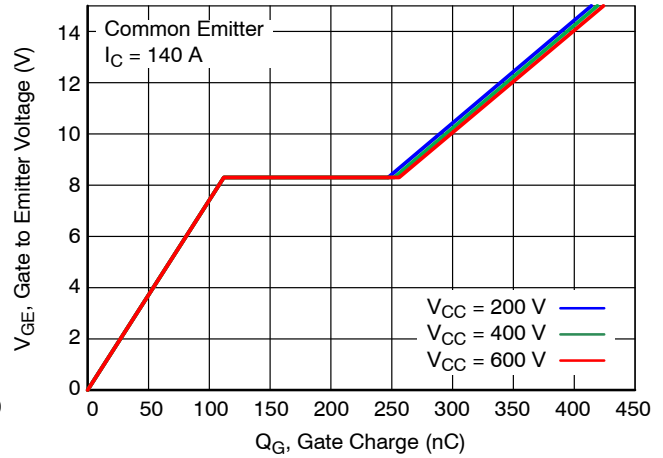


Figure 8. Gate Charge Characteristics

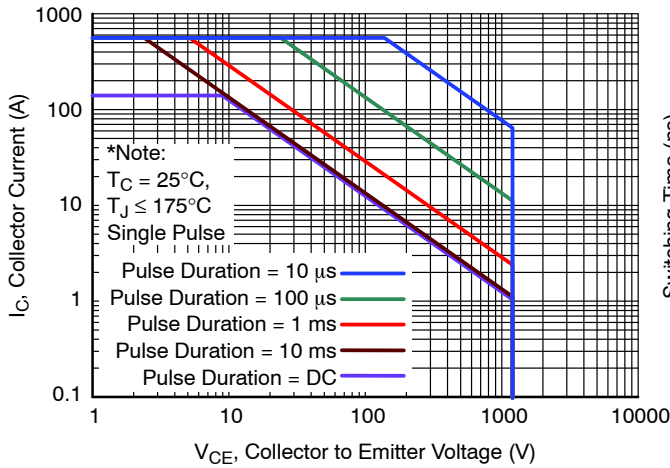


Figure 9. SOA Characteristics

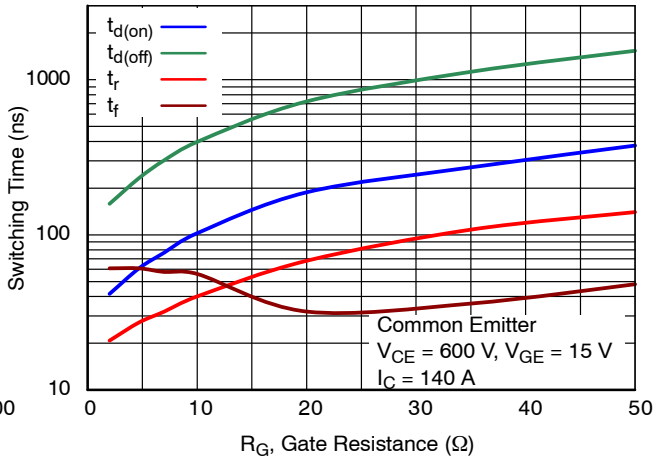


Figure 10. Switching Time vs. Gate Resistance ($T_J = 25^\circ\text{C}$)

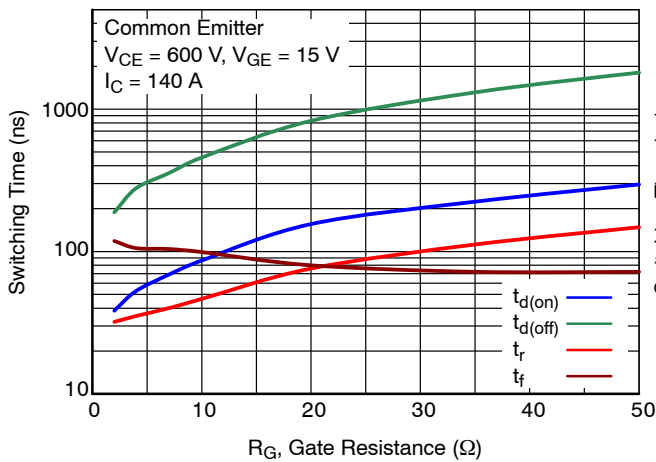


Figure 11. Switching Time vs. Gate Resistance ($T_J = 175^\circ\text{C}$)

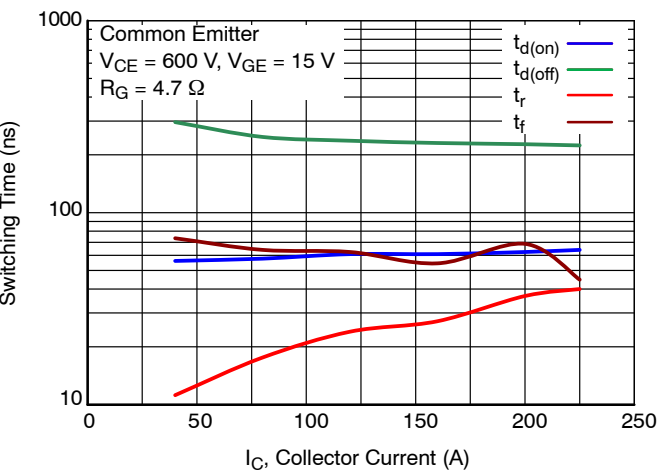


Figure 12. Switching Time vs. Collector Current ($T_J = 25^\circ\text{C}$)

TYPICAL CHARACTERISTICS

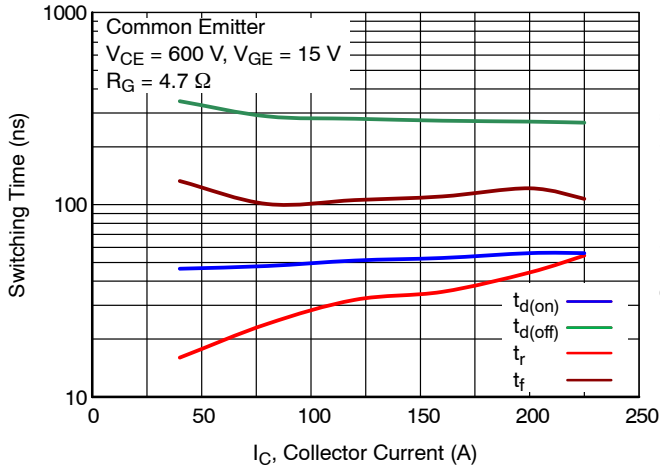


Figure 13. Switching Time vs. Collector Current ($T_J = 175^\circ\text{C}$)

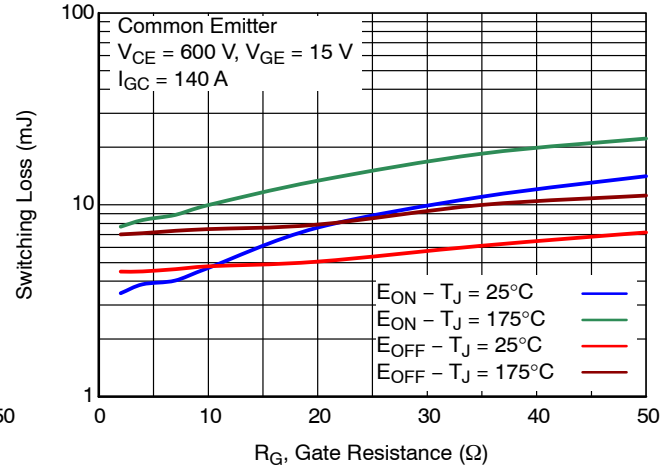


Figure 14. Switching Loss vs. Gate Resistance

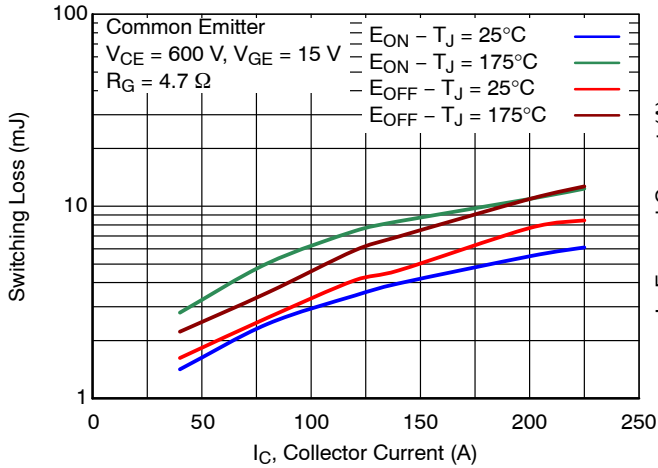


Figure 15. Switching Loss vs. Collector Current

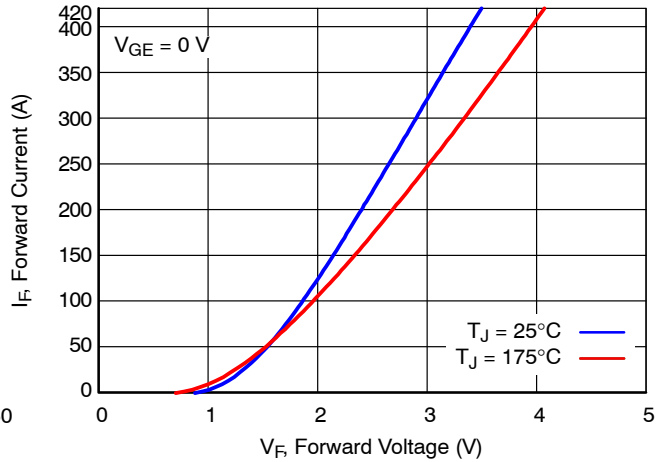


Figure 16. Diode Forward Characteristics

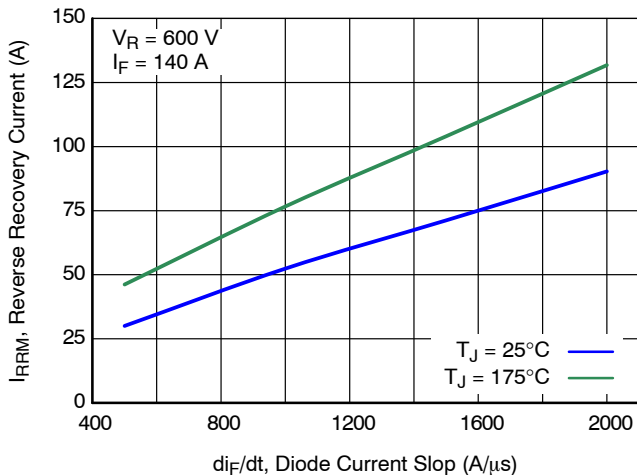


Figure 17. Diode Reverse Recovery Current

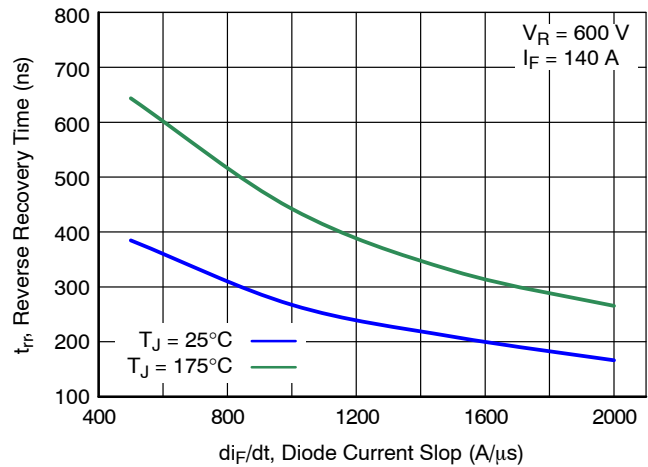


Figure 18. Diode Reverse Recovery Time

FGY4L140T120SWD

TYPICAL CHARACTERISTICS

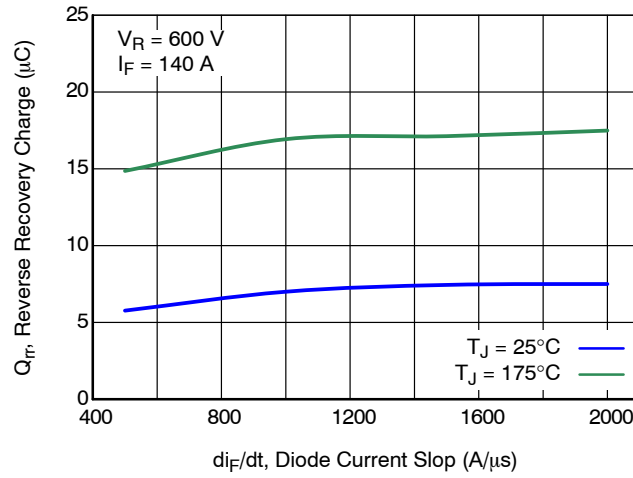


Figure 19. Diode Stored Charge

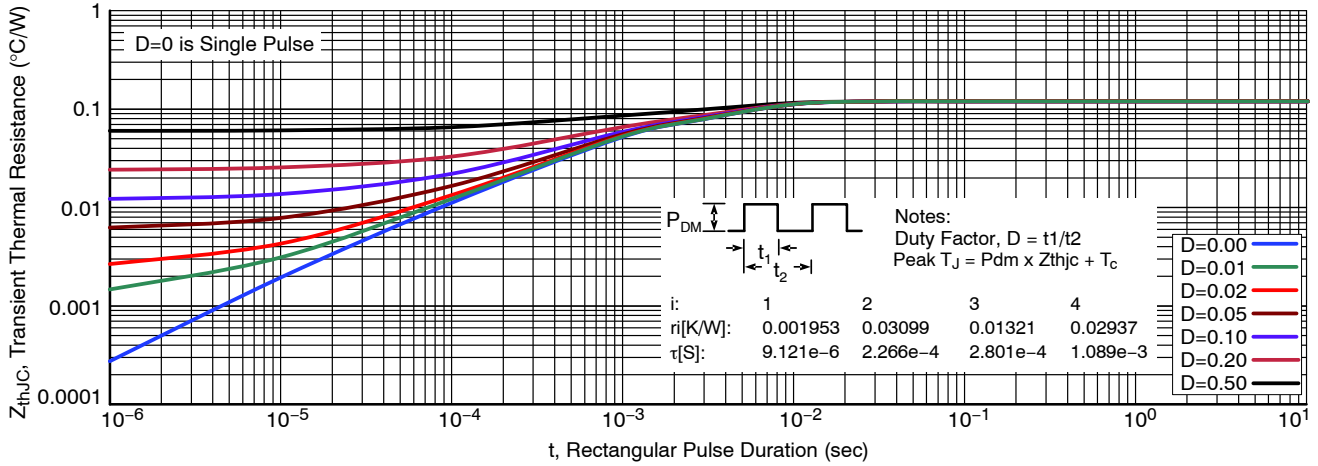


Figure 20. Max Transient Thermal Impedance of IGBT

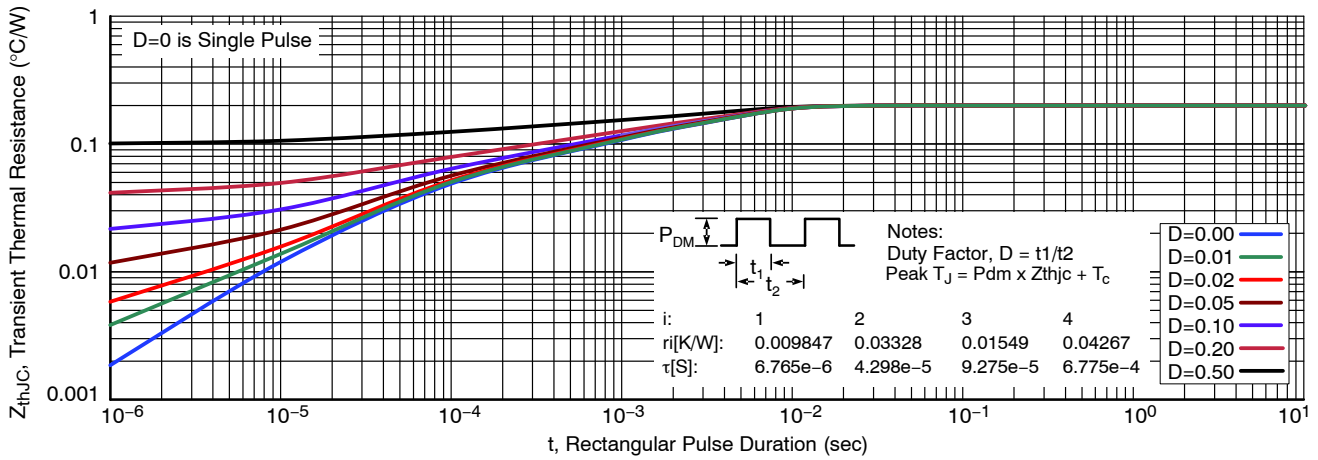
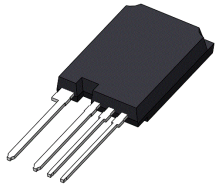
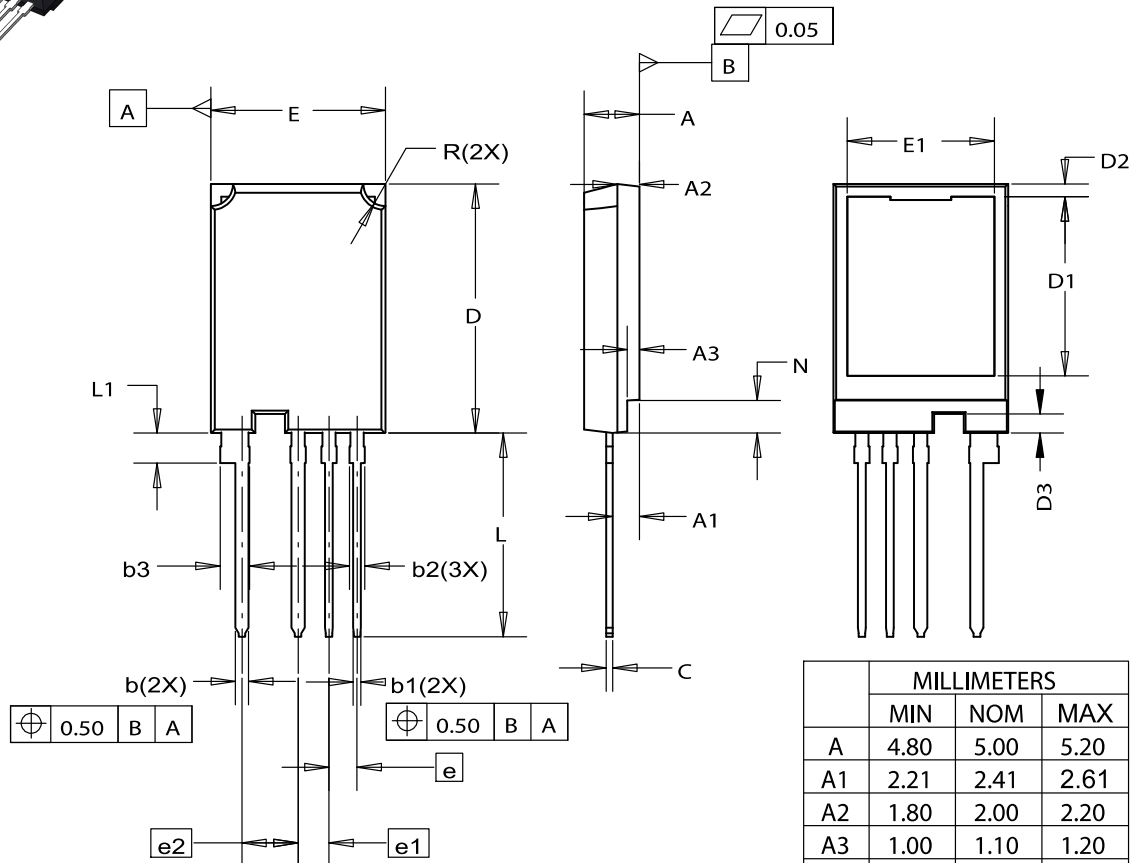


Figure 21. Max Transient Thermal Impedance of Diode



TO-247-PLUS-4L 15.80x22.54x5.00, 2.54P
CASE 340BW
ISSUE A

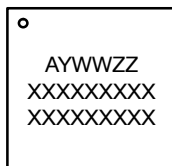
DATE 07 SEPT 2023



NOTES:

- A. NO INDUSTRY STANDARDS APPLIES TO THIS PACKAGE.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
D. DRAWING CONFORMS TO ASME Y14.5-2009.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

	MILLIMETERS		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.61
A2	1.80	2.00	2.20
A3	1.00	1.10	1.20
b	1.07	1.20	1.33
b1	0.57	0.70	0.83
b2	1.20	1.40	1.60
b3	2.47	2.67	2.87
c	0.50	0.60	0.70
D	22.34	22.54	22.74
D1	16.00	16.20	16.40
D2	0.96	1.16	1.36
D3	1.52	1.72	1.92
e	2.54BSC		
e1	2.79BSC		
e2	5.08BSC		
E	15.60	15.80	16.00
E1	13.10	13.30	13.50
L	18.12	18.42	18.72
L1	2.52	2.72	2.92
R	1.90	2.00	2.10
N	2.75	2.95	3.15

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